

REMARKS

Applicant respectively submits the above cited changes in order to correct errors in
the original application.

If there are any additional charges, please apply them to Deposit Account 02-2666.

Respectfully submitted,

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APPENDIX A

SPECIFICATION AND CLAIMS AMENDMENTS WITH MARKINGS TO SHOW

CHANGES MADE

IN THE SPECIFICATION:

Amended paragraphs with markings to show changes:

[0009] Fig. 3 shows an [and] embodiment of the invention having two integrated circuits connected to each other and to an underlying substrate through multiple insulated bond wires.

IN THE CLAIMS:

Please amend claims 1, 2, 8, 12, 14, 16, and 18, as indicated.

1. (Amended) An apparatus [insulated bond wire] comprising:
 - a bond wire;
 - an insulating material coating said bond wire; and
 - a first end of said bond wire connected to a bond pad.

2. (Amended) The insulated bond wire of claim 1 wherein said bond wire material is selected from a group consisting of [including] gold, silver, aluminum, and copper.

8. (Amended) An integrated circuit [A pair of bond wires] comprising:
a first bond wire;
an insulating material coating said first bond wire;
a first end of said first bond wire connected to a bond pad; and
a second bond wire crossing said first bond wire.

12. (Amended) The integrated circuit assembly of claim 11 wherein said substrate is selected from a group consisting of [including] printable circuit boards, aluminum lead frames, and fine pitch ball grid arrays.

14. (Amended) The integrated circuit assembly of claim 11 wherein said bond wire material is selected from a group consisting of [including] gold, silver, aluminum, and copper.

16. (Amended) The integrated circuit assembly of claim 15 wherein said substrate is selected from a group consisting of [including] printable circuit boards, aluminum lead frames, and fine pitch ball grid arrays.

18. (Amended) The integrated circuit assembly of claim 15 wherein said bond wire material is selected from a group consisting of [including] gold, silver, aluminum, and copper.